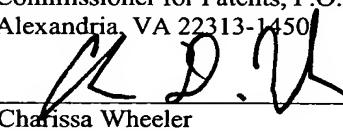


Sole Inventor

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Charissa Wheeler

## APPLICATION FOR UNITED STATES LETTERS PATENT

## S P E C I F I C A T I O N

TO ALL WHOM IT MAY CONCERN:

Be it known that I, **Young Ho SOHN**, a citizen of the Republic of Korea, residing at 891-10 Daechi-dong, Gangnam-gu, Seoul, Korea have invented new and useful **SIDE BRAZE PACKAGES**, of which the following is a specification.

## SIDE BRAZE PACKAGES

### FIELD OF THE DISCLOSURE

**[0001]** The present disclosure relates to semiconductor packages; and, more particularly, to side braze packages for enhancing packaging efficiency.

### BACKGROUND

**[0002]** Packaging is the process in which a semiconductor is enclosed for protection and to provide ease of handling and usage.

**[0003]** A side braze package is one of several types of packages. A conventional side braze package includes a lead installed at an outer wall of a main body having a groove and connected to an external power supply. Also, a semiconductor chip is bonded on the groove using an adhesive. A wire interconnects a bonding pad of the semiconductor chip to a contact line of the main body.

**[0004]** To increase integration efficiency of the package, since one semiconductor chip is embedded on the groove in the conventional side braze package, another package is stacked on the chip.

### BRIEF DESCRIPTION OF THE DRAWINGS

**[0005]** Fig. 1 is a cross sectional view of an example side braze package constructed in accordance with the teachings of the present disclosure.

**[0006]** Fig. 2 is a cross sectional view of another example side braze package constructed in accordance with the teachings of the present disclosure.

#### DETAILED DESCRIPTION

**[0007]** Fig. 1 is a cross sectional view of an example side braze package. Referring to Fig. 1, two semiconductor chips 18 and 22 are packaged in the side braze package.

**[0008]** In the side braze package of Fig. 1, a groove located in an upper portion of a main body 10 is made of a conductive braze. A lead 16 is formed on an outer wall of the main body 10. This lead 16 is connected to an external power supply. A first flip chip 22 is bonded on a lower portion of the groove through a solder bump 24 and a second flip chip 18 is stacked onto the first flip chip 22 by means of an adhesive 20 therebetween. Through holes 14 are formed from the upper portion to the lower portion around an inner sidewall of the groove to thereby penetrate a first line 12 connecting the lead 16 to the solder bump 24. Also, a second line 16 is connected to the lead through the through hole 14.

**[0009]** A pad of a second semiconductor chip 18 is wire bonded with the second wire 16. The groove is molded with an encapsulant 28. The main body 10 can be made of a ceramic material.

**[0010]** Fig. 2 is a cross sectional view of another example side braze package. Three semiconductor chips 108, 112 and 116 are packaged in the side braze package in the example of Fig. 2.

**[0011]** A lead 107 is formed on an outer wall of a main body 100. The main body 100 has first and a second grooves formed at an upper portion and a lower portion thereof with reference to a support layer 101. The lead 107 is connected to an external power supply. A first semiconductor chip 112 is flip chip bonded on a lower portion of the first groove through a solder bump 114. A second semiconductor chip 108 is stacked onto the first semiconductor chip 112 by means of an adhesive 110 therebetween. A through hole 104a is formed from the upper portion to the lower portion around an inner sidewall of the first groove to thereby penetrate a first line 103 connecting the lead 107 to the solder bump 114 formed on the support layer 101. Also, the lead 107 is connected to a second line 106 through a second through hole 104b penetrating the support layer 101. Also, a pad of the second semiconductor chip 108 is connected to the second line 106 using a wire 118. A third semiconductor chip 116 is flip chip bonded using the solder bump 114 formed under the support layer 101 and connected to the first line 103. A vacant space in the groove is molded using an encapsulant.

**[0012]** In other examples, more than two semiconductor chips, (e.g., four semiconductor chips) can be packaged in the main body of the side braze package of Fig. 2. For example, a fourth semiconductor (not shown) can be further mounted under the third semiconductor 116. In such an example, a through hole for connecting the line of the third semiconductor chip 116, a wire for connecting a pad of the fourth semiconductor chip with the line connected to the through hole may be further needed.

**[0013]** As described above, since two or more semiconductor chips can be mounted in the side braze package, packaging efficiency can be enhanced.

**[0014]** From the foregoing, persons of ordinary skill in the art will appreciate that side braze packages have been disclosed which are capable of incorporating two or more semiconductor chips to thereby enhance packaging efficiency.

**[0015]** An illustrated example side braze package includes: a lead located at a sidewall of a main body having a groove, and connected to an external power supply; a first semiconductor chip being flip chip bonded on the groove through a solder bump; a second semiconductor chip being stacked on the first semiconductor chip; a first through hole formed from an upper portion to a lower portion around an inner sidewall of the groove; a first line connected to the lead through the solder bump and the first through hole; a second line connected to the lead through the first through hole; and a wire for connecting a pad of the second semiconductor to the second line.

**[0016]** Although certain example methods and apparatus have been described herein, the scope of coverage of this patent is not limited thereto. On the contrary, this patent covers all methods, apparatus and articles of manufacture fairly falling within the scope of the appended claims either literally or under the doctrine of equivalents.